

OT2-SAC0307-T3

Rev: 16.1

Date	2021.06.28
Language	English
SDS	950612



SUMMARY

Pb-free - Low Silver, No-Clean solder paste - Anti tombstoning - Halide/Halogen free

PASTE	OT2-SAC0307-T3
PROCESS	
No-Clean process	9
Post-solder cleaning	9

INDUSTRY APPLICATION	
Standard electronics	9
Industrial electronics	9
Hi-Rel electronics (automotive)	8

PROCESS CAPABILITY	
Squeegee	9
ProFlow	TBD
Pb-free Profile Air, short	9
Pb-free Profile Air, long	9
Pb-free process N2	9
Vapor phase process	8
Shiny joint appearance	6
Cosmetic cleanliness	9
ICCT compatible	9
Conformal coating	8

Legend	
<i>Especially made for this purpose</i>	9 - 10
<i>Generally qualified for this purpose</i>	7 - 8
<i>Generally usable, but not the best choice</i>	5 - 6
<i>Generally not usable for this purpose</i>	3 - 4
<i>Wrong choice</i>	1 - 2

Check material compatibility with every process change!

Industrial chemical product.

Read MSDS before use.

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CLASSIFICATION

DIN-EN-29454-1: 1994	1.1.3.C
IPC-J-STD-004-A: 2004	ROL0
IPC-J-STD-005: 1995 (Powder)	T3
Particle size	[µm] 25-45

PROPERTIES

Flux code	OT2	
Alloy Code	SAC0307	
Alloy composition	Sn99Ag0.3Cu0.7	
Liquidus	[°C]	227
Solidus	[°C]	217
Recommended peak temp.	[°C]	232-260
Acid number	[mg KOH/g]	139.5
Flux	[% w/w]	12.1
Residues	Colorless	
Tackiness Malcom TK1	JIS-Z-3284	[gf] @ 0h 120

TEST REPORTS

IPC/ANSI-J-STD-005	Compliant	
Certificate of Compliance	Website	
RoHS Compliant	Available	
Application Note	EN/DE	
Copper Mirror	IPC-TM-650 2.3.32	Pass
Halides	IPC-TM-650 2.3.33	[Silver Chromate] Pass
Halide	IPC-TM-650 2.3.35.1	[Fluoride by Spot] Pass
Copper Corrosion	IPC-TM-650 2.6.15	Pass
SIR	IPC-TM-650 2.6.3.3	Pass
ECM	IPC-TM-650 2.6.14.1	Pass

PACKAGING AND STORAGE

Packaging jar	PP [g]	500
Packaging cartridge	HDPE [g]	650
Packaging cartridge	HDPE [g]	1300
Packaging Cassette Pro-Flow	[g]	800
Minimum shelf-life in months	4-10 °C	12